



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Warren M. Farnworth

Serial No.: 10/043,468

Filed: January 10, 2002

For: METHOD OF FORMING
OVERMOLDED CHIP SCALE PACKAGE
AND RESULTING PRODUCT

Confirmation No.: 7094

Examiner: K. Nguyen

Group Art Unit: 2823

Attorney Docket No.: 2269-3085.4US
(96-1033.04/US)

Notice of Allowance Mailed:

January 2, 2004

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

March 19, 2004
Date

Doreen Neumann
Signature

Doreen Neumann
Name (Type/Print)

AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)

Mail Stop ISSUE FEE
Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

Amendments to the Specification begin on page 3 of this paper.

Amendments to the Abstract appear on page 10 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 11 of this paper.

Remarks begin on page 17 of this paper.